

<b>PCN Number:</b>	20200908001.1		<b>PCN Date:</b>	Sep 14, 2020	
<b>Title:</b>	Qualification of RFAB as an additional Fab site option & bond wire diameter reduction for select devices				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>		<b>Dept:</b>	Quality Services	
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Dec 14, 2020		<b>Estimated Sample Availability:</b>	Date provided at sample request.	
<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input checked="" type="checkbox"/>	Wafer Fab Process
	<input type="checkbox"/>		Part number change		
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option for the selected devices listed below in the product affected section.					
<b>Current Fab Site</b>			<b>Additional Fab Site</b>		
<b>Current Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>	<b>Additional Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>
Vanguard	CMOS	200 mm	RFAB	LBC9	300 mm
Additionally, there will be a bond wire diameter reduction as follows:					
<b>What</b>		<b>Current</b>		<b>New</b>	
Bond wire/Diameter		Cu/0.96		Cu/0.80	
Qual details are provided in the Qual Data Section.					
<b>Reason for Change:</b>					
Continuity of Supply					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Anticipated impact on Material Declaration</b>					
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI ECO website</a> .		
<b>Changes to product identification resulting from this PCN:</b>					
<b>Current:</b>					
Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
Vanguard	VAN	TWN	HSINCHU		
<b>New Fab Site:</b>					
New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
RFAB	RFB	USA	Richardson		
Sample product shipping label (not actual product label)					



MADE IN: Malaysia  
2DC: 20:



(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483I2  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SHE (21L) CCO:USA  
(22L) ASO: MLA (23L) ACO: MYS

MSL 2 / 260C / 1 YEAR SEAL DT  
MSL 1 / 235C / UNLIM 03/29/04

OPT:  
ITEM: 39  
LBL: 5A (L) TO: 1750

**Product Affected:**

OPA4374AID	OPA4374AIDR	OPA4374AIDRG4
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**Qualification Report**

Approve Date 08-May-2020

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: OPA4374AIDR	QBS Product Reference: TLV9064ID	QBS Process Reference: TLV62568DBV	QBS Package Reference: TLV9054IDR
AC	Autoclave 121C	96 Hours	-	-	3/231/0	-
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	Pass	Pass
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	3/3000/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	1/77/0	3/231/0	3/231/0
HBM	ESD - HBM	4000 V	-	1/3/0	1/3/0	1/3/0
CDM	ESD - CDM	1500 V	-	1/3/0	2/6/0	1/3/0
HTOL	Life Test, 150C	300 Hours	-	1/77/0	3/231/0	1/77/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	1/76/0	3/231/0	3/231/0
LU	Latch-up	(per JESD78)	-	1/6/0	2/12/0	1/6/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	-	Pass	Pass
TC	Temperature Cycle, -65/150C	500 Cycles	-	1/77/0	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	1/77/0	-	3/231/0
WBP	Bond Pull	Wires	1/76/0	-	-	-
WBS	Ball Bond Shear	Wires	1/76/0	-	-	-

- QBS: Qual By Similarity
  - Qual Device s qualified at LEVEL2-260C: OPA4374AIDR
  - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
  - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
  - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**  
Qualified Pb-Free (SMT) and Green

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